APPLICATION FOR EXTENSION OF ESCC TECHNOLOGY FLOW APPROVAL

Component Title:

Thin Film Technology for Chip, Wraparound, Single and

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Network Resistors, Fixed Executive **CNES** Date: 18/01/2021 287G Member 1 Technology Flow submitted for Extension of Qualification Approval: SUMMARY DESCRIPTION COMPONENTS PROPOSED FOR QUALIFICATION TEST STRUCTURES P: Single resistor 0402, 0603, P0402, P0603, P0805, P1206 and P2010 By form factor : 0805, 1206, 2010 chip with min., critical resistance and max. ESCC4001023 var. 15 and 13, 14(*) PRA: 2 to 8 resistors of similar ESCC4001023 var. 01, 05 (*) and 09 ESCC4001023 var. 02, 06 (*) and 10 ESCC4001023 var. 03, 07 (*) and 11 value, based on 0603 (PRA 100), PRA100, PRA135, PRA182 with min., 0805 (PRA135) or 1206 (PRA182) critical resistance and max. values. units ESCC4001023 var. 04, 08 (*) and 12 ESCC4001025 var. 01 to 07, 22 to 28 ESCC4001025 var. 08 to 14, 29 to 35 CNW: 2 to 8 resistors with at least two different values with the same ESCC4001025 var. 15 to 21, 36 to 42 form factor as PRA Substrate: Alumina (*) Note that gold finish variants are not intended Resistive layer: Nickel Chromium for de-golding and tinning Protection : Silicium nitride Termination : Nickel Barrier Processes: Thin Film deposition Finish: SnPbAg or Au Component Manufacturer 2 Location of Manufacturing Plant(s) 3 4 Date of original qualification approval: 15/02/2009 Date: VISHAY SA Nice (France) Division Résistances de Très Certificate Ref No. 287 **Haute Précision** ESCC Specifications used for Deviations to LVT testing and Detail Qualification Extension Report 5 6 7 Specification used: Maintenance testing: reference and date: 4001 4 QML Quality Synthesis reports : □ Yes ⊠ (supply details in Generic: Issue: Box 15) QML 2019 Synthesis, 15/01/2020 QML 2020 Synthesis, 06/01/2021 Deviation from current Specifications: 11 Detail(s): 4001/023 Issue: 4001/025 7 ⊠ Yes □ (Supply details) 8 Summary of procurement or equivalent test results during current validity period in support of this application (those to ESCC listed first) Customer Component LVT Date code Quantity Delivered PHR1206 2025 (3), 2028 (2) TAS Belgium, Sodern, LVT1 2019: 119 157 ALTER, TTI, RUAG, TAS It, TAS Fr ... PHR0805 I VT1 1925, 1926 (2) 2020: 76 935 PHR0603 2028, 2029 (2) IVT1 PHR0603 LVT3 1928 TTI, Cyphen Ltd, PRA / CNW LVT3 2007 2019: 23 854 2020: 6 791 2019: 8 595 ALTER, Vishay Dale, PERR 0805 TTI, ECOMAL ... PFRR 0603 2020: 8 450 PFRR 1206 9 JP Bussenot, CNES 10 PID changes since last maintenance of qualification Current PID Verified by: None П Name of Excutive Representative Minor* \boxtimes Ref No: PID-TFD P PRA CNW Major* *Provide details in box: 23/07/2020 Issue: 11 Date: 19 Rev. 27/05/2020 Date 11 Current Manufacturing facilities surveyed by: S. Hernandez, ESA & JP Bussenot, CNES 07/02/2019 (Name of Executive Representative) (Date) Satisfactory: Explain No CNES - DCT/AQ/CQ/2019-003325 Report Reference:



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	Executive Member:	CNES		Date: 18/01/2021	287G
Failure Analysis, DPA, NCCS ava	ilable: Yes	□ No	⊠ (Supply data)		12
The undersigned hereby certifies on behalf that the appropriate documentation has bee (except as stated in box 15;) - that the report CNES as the responsible Executive Members.	en evaluated; - that full rts and data are availa	compliance to ble at the ESC	all ESCC requirements i C Executive and therefor	s evidence re applies on behalf of	13
Date: 18/01/2021				JP. BUSSEN	
Date. 10/01/2021				(Signature of the Executive	
				(5	
Continuation of Boxes above:					14
Box 6: Periodic Testing is defined in par	ragraph 6 of the Tech	nology Flow I	PID (See page 3)		

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Executive Member: CNES

Date: 18/01/2021

B.Schade: Head of the Product Assurance and Safety Department

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Non compli	ance to ESCC requirements:					15
No.:	Specification		Paragraph		Non compliance	
1	4001	Chart F4		Chart F4 te implements in PID para	sting replaced with the ation of periodic testing as des graph 6.3	cribed
Additional ta noncomplia	asks required to achieve full cor nce:	npliance for ESCC quali	fication or rationale for acce	ptability of		16
None						
Executive N	Manager Disposition					17
Application Action / Rer		No 🗆				
					Digitally signed	
				5.4	Digitally signed by Britta Schade Date: 2021.02.2	e 3
Date:					18:49:11 +01'00	'



APPLICATION FOR EXTENSION OF ESCC QUALIFICATION APPROVAL

Component Title: Thin Film Technology for Chip, Wraparound, Single and Network

Resistors, Fixed

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ANNEX 1: LIST OF TESTS DONE TO SUPPORT EXTENSION OF QUALIFICATION

Tests conducted in compliance with:

ESCC 4001 generic specification; Chart F4 (for ESCC/QPL parts); or PID-TFD **P PRA CNW Issue 11** (for ESCC/QML parts)

Tests vehicle identification/description:

	PHR0402 dc 1822 (19K6), 1939 (3K), 1921 (50R) PHR0603 dc 1829 (200K), 1914 (10R), 1907 (61R9), 2005 (165K), 2017 (66K5)	PHR1206 dc 1906 (75R), 1937 (6K49), 2007 (562K) PHR2010 dc 2009 (511K)
ı	PHR0805 dc 1914 (15R), 2017 (7K5)	PRAHR dc 1903 (2K), 1917 (10K) CNWHR dc

Detail Specification reference: 4001/023 & /025

	etail Specification reference. 400 m/25 4 m/							
Char		Test	Tick when done	Conditions	Date Code	Tested Qty	N° of Rejects	Comments if not performed. Comments on Rejection
		Mounting	⊠	IEC 60115-1 clause 4.31	1822 1829 1914 1906 1939 1937 1903 1917 1921 1907 2005 2007 2009 2017	10 10 2 x 5	0	
dn	do	Rapid Change Of Temperature	⊠	IEC 60068-2-14	1822 1829 1914 1906 1939 1937 1903 1917 1921 1907 2005 2007 2009 2017	10 10 2 x 5 5 5 5 5 5 5 5 5 5 5 5 5 5 2 x 5	0	
abgro	5	Vibration		IEC 60068-2-6				NA
Environmental //Mechanical Subgroup		Climatic test Sequence	⊠	ESCC 4001, Para 8.10	1822 1829 1914 1906 1939 1937 1921 1907 2005 2007 2009 2017	10 10 2 x 5 5 5 5 5 5 5 5 5 5	0	
		Seal Test		IEC 60068-2-17				NA
		Mounting	⊠	IEC 60115-1 clause 4.31	1822 1829 1914 1906 1939 1937 1921 1907 2005 2007 2009 2017	3 3 2 x 2 2 2 2 3 3 3 2 2 2 2 2 2 2 2 2 2 2 2 2	0	
		Robustness of Terminations	×	IEC 60068-2-21	1822 1829 1914 1906 1939 1937 1921 1907 2005 2007 2009 2017	2 x 2 2 2 2 3 3 3 2 2 2 2 2 2 2 2 2 2 2	0	Adhesion + Substrate bending

	Climatic test Sequence	×	ESCC 4001, Para 8.10	1822 1829 1914 1906 1939 1937 1921 1907 2005 2007 2009	3 3 2 x 2 2 2 2 3 3 3 2 2 2 2 2 2 2 2 2 2 2 2 2	0	
	Seal Test		IEC 60068-2-17	2011	2		NA
	Resistance to Soldering Heat	⊠	IEC 60068-2-20	1822 1829 1914 1906 1939 1937 1903 1917 1921 1907 2005 2007 2009 2017	3 3 2 x 2 2 2 2 2 2 2 3 3 2 2 2 2 2 2 2 2 2 2 2	0	
	Mounting		IEC 60115-1 clause 4.31				
	Climatic test Sequence	×	ESCC 4001, Para 8.10	1939 1937 2005 2007 2009 2017	2 2 2 2 2 2 2 x 2	0	
	Seal Test		IEC 60068-2-17				NA
	Mounting		IEC 60115-1 clause 4.31				
	Insulation Resistance	⊠	ESCC 4001, Para 8.3.1.2	1914 1906 1939 1937 1921 1907 2005 2007 2009 2017	2 x 5 5 5 5 5 5 5 5 5 5 2 x 5	0	
	Voltage Proof	×	ESCC 4001, Para 8.3.1.3	1914 1906 1939 1937 1921 1907 2005 2007 2009 2017	2 x 5 5 5 5 5 5 5 5 5 5 2 x 5	0	
ubgroup	Mounting	×	IEC 60115-1 clause 4.31	1914 1906 1903 1917 1921 1907	2 x 5 5 10 10 10 10	0	
Endurance Subgroup	Operating Life	⊠	ESCC 4001, Para 8.13	1914 1906 1903 1917 1921 1907	2 x 5 5 10 10 10 10	0	PHR Low Ohmic value PHR Low Ohmic value PRAHR 100I2B PRAHR 100I2B PRAHR 100I2B PHR Low Ohmic value PHR Low Ohmic value
	Seal Test		IEC 60068-2-17	16			NA
Assembly Capability Subgroup	Solderability	×	IEC 60068-2-20	1822 1829 1914 1906 1939 1937 1903 1917 1921 1907 2005 2007 2009 2017	3 3 2 x 2 2 2 2 5 5 3 3 2 2 2 2 2 x 2 2 2 x 2 2 x 2 x	0	
₹	Permanence of marking		ESCC 24800	1903	5	0	PRA / CNW
Failure Rate Endurance Subgroup		×	ESCC 4001, Para 8.13	1917 Febr. '19 to January '20 - Febr. '20 to May '21	5 600 310 - 80 - to come -	0 -	2 000H 4 000H 6 000H 8 000H
				May '21	-		

	Seal Test		IEC 60068-2-17				NA	
Additional Tests	High & Low Temp (Temperature Coefficient)	⊠	ESCC 4001	1822 1829 1914 1906 1939 1937 1903 1917 1921 1907 2005 2007 2009 2017	5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5	0		



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NOTES ON THE COMPLETION OF THE APPLICATION FORM FOR ESCC QUALIFICATION EXTENSION APPROVAL

ENTRIES	
Form heading	shall indicate: - the title of the component as given in its detail specification or the name of the series, family; - the Executive Member; - the entering date; - the certificate number and its sequential suffix.
Box 1	shall provide details given in the table; in particular there shall be listed: - the variants or range of variants; - the range of components (the ESCC code is recommended to indicate the values or values range, the tolerance, the voltage, etc); the designation given in the detail specification as 'base on'; - under Test Vehicle enter either an ESCC code or the specific characteristic capable of identifying the component tested (e.g., voltage of coil for a relay); - under component similar enter a cross if relevant.
Box 2; 3 and 4	As per QPL entry; otherwise, an explanation of the changes must be supplied.
Box 5	Will show the ESCC Generic and Detail specifications, including issue number and revision letter, current at the time the tests reported were performed. If the specifications are different from those current on the date of the application, see Box 6.
Box 6	Will show the deviations from the Generic and Detail Specifications listed in Box 5, in particular deviations from testing. In case of deviations this must be listed in Box 15. In case the referenced specification in Box 5 have currently a different issue and/or revision indicate also whether the test data deviates or not from such current documents.
Box 7	Must reference the report(s) supplied in support of the application.
Box 8	Should provide the details of procurement to the full ESCC System, documentation of all of which should already have been delivered to the ESCC Executive under the terms of the relevant Generic Specification. An appropriate table has been drawn in this box.
Box 9	If the PID evolved after the Original Qualification or after the last Extension of Qualification, adequate details of such evolution shall be provided together with the reasons for the changes. Major changes shall be clearly marked.
Box 10	Identify the current PID issue status, date and actual date of verification. The date of verification of the current PID should be arranged as close as possible to the required date of extension.
Box 11	This box can be completed only after a physical visit to the plant to confirm that no unexplained changes occurred and that the practices, procedures, material, etc. used in manufacturing the components are as described in the PID. This survey shall be carried out in accordance with the requirements of ESCC Basic Specification No. 20200 and its findings shall be recorded.
Box 12	Provide details of, or reference to, any Destructive Physical Analysis (DPA) and Failure Analysis reports as well as any Nonconformance(s) (NCCS) occurred during the qualification validity period, stating if established corrective action have produced satisfactory results.
Box 13	Enter only the name of the Executive Member (i.e., CNES, DLR, ESTEC, etc.) and the signature of the responsible Executive Coordinator.
Box 14	To be used when there is a need to expand any of the boxes from 1 through 12. Identify box affected and reference the Box 14 in the relevant Box. Box 14 can be broken into 14a, 14b, etc. if several boxes have to be expanded.
Box 15	Fill in Table as requested.
Box 16	Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.
Box 17	All Executive Manager recommendations on the application itself, special conditions or restrictions, modifications of the QPL or QML entry, letters to the manufacturer, etc. shall be entered clearly in Box 19, signed by the representative for ESA, and dated.
Box 18	Fill in Table as requested.
Box 19	Confidential Details of PID changes including those of a confidential nature, shall be provided.
Box 20	State noncompliance with reference to specification(s) and paragraph(s). To simplify reference in Box 16 each nonconformance shall be sequentially numbered. If relevant state 'None'.
Box 21	Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.
Box 22	Additional Comments.